

IXFT10N100 Datasheet

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DiGi Electronics Part Number	IXFT10N100-DG
Manufacturer	IXYS
Manufacturer Product Number	IXFT10N100
Description	MOSFET N-CH 1000V 10A TO268
Detailed Description	N-Channel 1000 V 10A (Tc) 300W (Tc) Surface Mount TO-268AA



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Purchase and inquiry

Manufacturer Product Number:

IXFT10N100

Series:

HiPerFET™

FET Type:

N-Channel

Drain to Source Voltage (V_{dss}):

1000 V

Drive Voltage (Max R_{ds} On, Min R_{ds} On):

10V

V_{gs(th)} (Max) @ I_d:

4.5V @ 4mA

V_{gs} (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (T_J)

Supplier Device Package:

TO-268AA

Base Product Number:

IXFT10

Manufacturer:

IXYS

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (I_d) @ 25°C:

10A (T_c)

R_{ds} On (Max) @ I_d, V_{gs}:

1.20hm @ 5A, 10V

Gate Charge (Q_g) (Max) @ V_{gs}:

155 nC @ 10 V

Input Capacitance (C_{iss}) (Max) @ V_{ds}:

4000 pF @ 25 V

Power Dissipation (Max):

300W (T_c)

Mounting Type:

Surface Mount

Package / Case:

TO-268-3, D³Pak (2 Leads + Tab), TO-268AA

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



HiPerFET™ Power MOSFETs

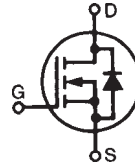
N-Channel Enhancement Mode
High dv/dt, Low t_{rr} , HDMOS™ Family

Preliminary data sheet

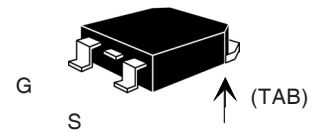
IXFT 10 N100
IXFT12 N100

V_{DSS}	I_{D25}	$R_{DS(on)}$
1000 V	10 A	1.20 Ω
1000 V	12 A	1.05 Ω

$t_{rr} \leq 250$ ns



TO-268 Case Style



G = Gate,
S = Source,
TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	1000	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1$ M Ω	1000	V
V_{GS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	10N100: 10 12N100: 12	A
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	10N100: 40 12N100: 48	A
I_{AR}	$T_C = 25^\circ\text{C}$	10N100: 10 12N100: 12	A
E_{AR}	$T_C = 25^\circ\text{C}$	30	mJ
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100$ A/ μs , $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2$ Ω	5	V/ns
P_D	$T_C = 25^\circ\text{C}$	300	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ\text{C}$
M_d	Mounting torque	1.13/10	Nm/lb.in.
Weight		TO-268 = 6	g

Features

- International standard package
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance - easy to drive and to protect
- Fast intrinsic Rectifier

Applications

- DC-DC converters
- Synchronous rectification
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Temperature and lighting controls
- Low voltage relays

Advantages

- Surface mountable, high power package
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0$ V, $I_D = 3$ mA	1000		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4$ mA	2.0		4.5 V
I_{GSS}	$V_{GS} = \pm 20$ V _{DC} , $V_{DS} = 0$			± 100 nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$, $T_J = 25^\circ\text{C}$ $V_{GS} = 0$ V, $T_J = 125^\circ\text{C}$			250 μA 1 mA
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300$ μs , duty cycle $d \leq 2$ %	10N100 12N100		1.20 Ω 1.05 Ω

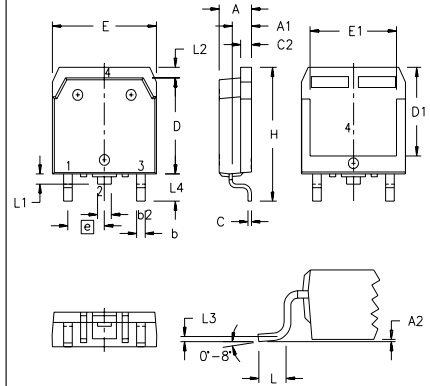
IXYS

IXFT 10N100 IXFT 12N100

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)			
		min.	typ.	max.	
g_{fs}	$V_{DS} = 10\text{ V}; I_D = 0.5 \cdot I_{D25}$, pulse test	6	10	S	
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		4000	pF	
C_{oss}			310	pF	
C_{rss}			70	pF	
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 2\ \Omega$ (External),		21	50	ns
t_r			33	50	ns
$t_{d(off)}$			62	100	ns
t_f			32	50	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		122	155	nC
Q_{gs}			30	45	nC
Q_{gd}			50	80	nC
R_{thJC}			0.42	KW	

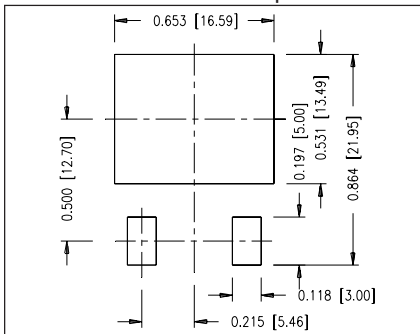
Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)			
		min.	typ.	max.	
I_S	$V_{GS} = 0\text{ V}$	10N100 12N100		10 12	A A
I_{SM}	Repetitive; pulse width limited by T_{JM}	10N100 12N100		40 48	A A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			1.5	V
t_{rr}	$I_F = I_S$ $-di/dt = 100\text{ A}/\mu\text{s}$, $V_R = 100\text{ V}$	$T_J = 25^\circ\text{C}$		250	ns
		$T_J = 125^\circ\text{C}$		400	ns
Q_{RM}		$T_J = 25^\circ\text{C}$	1		μC
		$T_J = 125^\circ\text{C}$	2		μC
I_{RM}		$T_J = 25^\circ\text{C}$	10		A
		$T_J = 125^\circ\text{C}$	15		A

TO-268 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

Min Recommended Footprint



IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343 6,583,505

Fig. 1. Output Characteristics

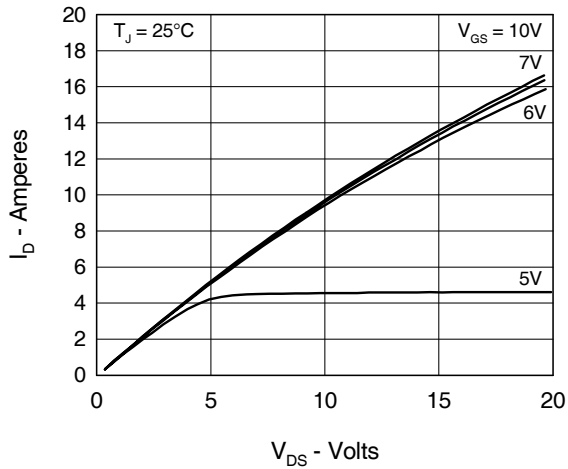


Fig. 2. Input Admittance

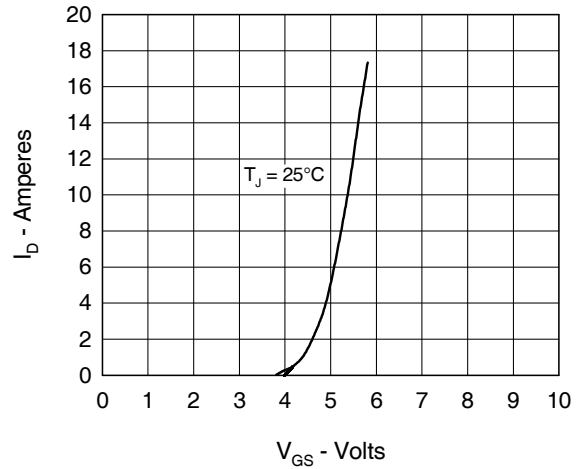
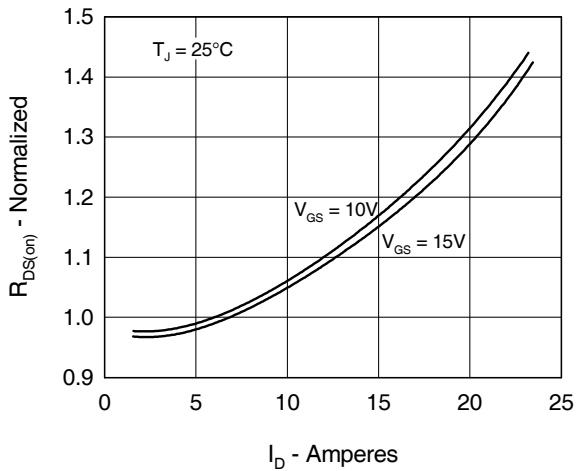
Fig. 3. $R_{DS(on)}$ vs. Drain Current

Fig. 4. Temperature Dependence of Drain to Source Resistance

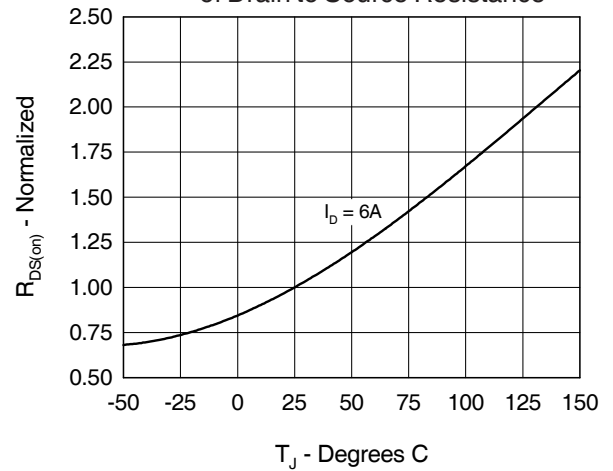


Fig. 5. Drain vs. Case Temperature

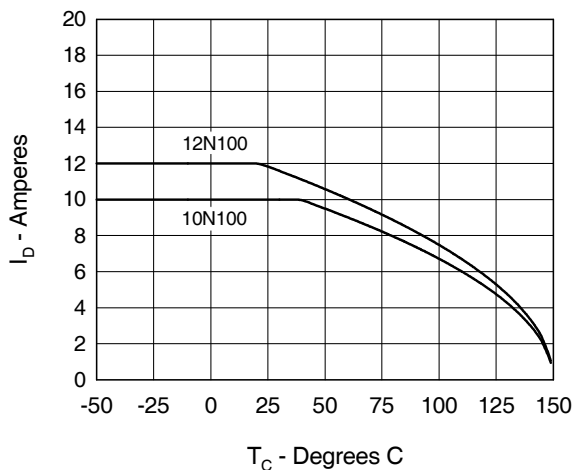


Fig. 6. Temperature Dependence of Breakdown and Threshold Voltage

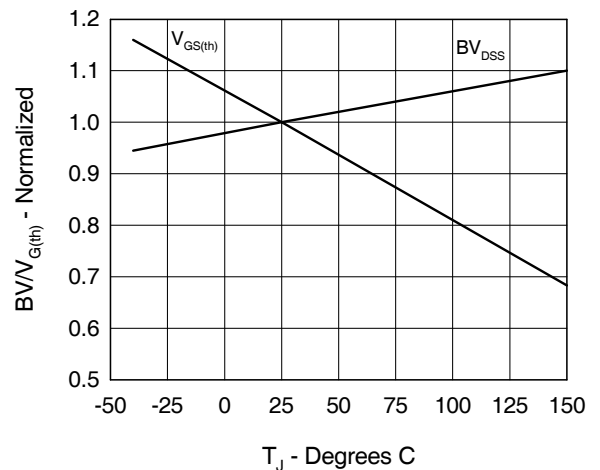




Fig. 7. Gate Charge Characteristic Curve

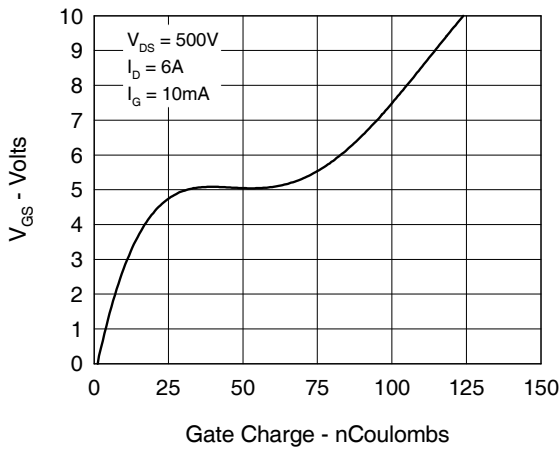


Fig. 8. Capacitance Curves

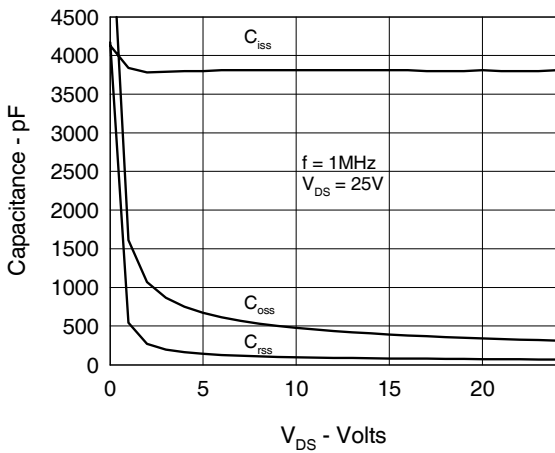


Fig. 9. Source Current vs. Source to Drain Voltage

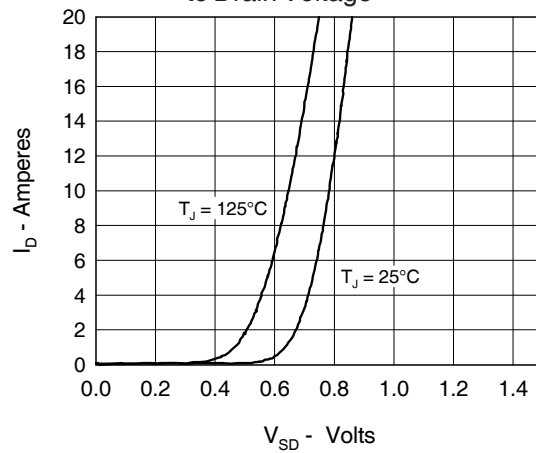
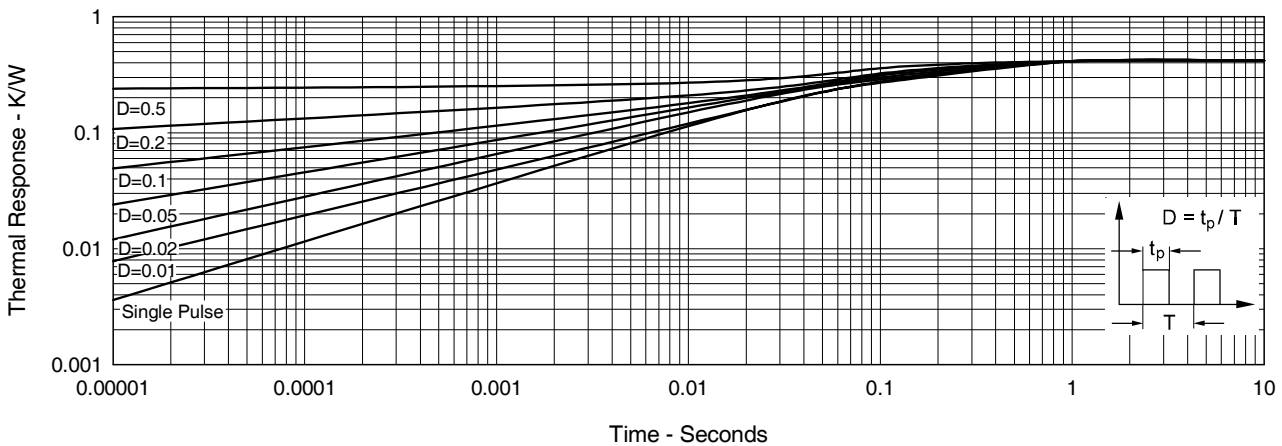


Fig.10.

Transient Thermal Impedance



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